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| <b>(51) International Patent Classification</b><br><b>C11D 9/04</b>                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                            | <b>A1</b> | <b>(11) International Publication Number:</b> <b>WO 00/44867</b><br><b>(43) International Publication Date:</b> 3 August 2000 (03.08.00)                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                             |
| <b>(21) International Application Number:</b> PCT/US00/00116<br><b>(22) International Filing Date:</b> 4 January 2000 (04.01.00)<br><b>(30) Priority Data:</b><br>09/238,851 27 January 1999 (27.01.99) US<br><b>(71) Applicant:</b> ASHLAND INC. [US/US]; P.O. Box 2219, Columbus, OH 43216 (US).<br><b>(72) Inventors:</b> PETERS, Daryl, W.; 111 Kennedy Mill Road, Stewartsville, NJ 08886-2402 (US). WARD, Irl, E.; 1493 Amherst Court, Bethlehem, PA 18015 (US).<br><b>(74) Agents:</b> CONNAUGHTON, Martin; Ashland Inc., P.O. Box 2219, Columbus, OH 43216 (US) et al. |           | <b>(81) Designated States:</b> AE, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, UZ, VN, YU, ZA, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG).<br><br><b>Published</b><br><i>With international search report.<br/>Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.</i> |
| <b>(54) Title:</b> ACIDIC COMPOSITION CONTAINING FLUORIDE FOR REMOVAL OF PHOTORESISTS AND ETCH RESIDUES<br><br><b>(57) Abstract</b><br><br>The present invention relates to compositions useful in removing photoresist and organic and inorganic residues and processes for removal of photoresists and etch residues. The compositions are aqueous, acidic compositions containing fluoride and organic polar solvents. The compositions are free of glycols and have a low surface tension and viscosity. Corrosion inhibitors are optionally present.                      |           |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                      |